PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT4857771

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
KENJI OUCHI	02/28/2018

RECEIVING PARTY DATA

Name:	TOKYO ELECTRON LIMITED
Street Address:	3-1 AKASAKA 5-CHOME, MINATO-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	107-6325

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15915782

CORRESPONDENCE DATA

Fax Number: (408)938-9069

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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ATTORNEY DOCKET NUMBER:	TELF-0136-02S01US
NAME OF SUBMITTER:	ANTHONY C. MURABITO
SIGNATURE:	/Anthony C. Murabito/
DATE SIGNED:	03/08/2018
	This document serves as an Oath/Declaration (37 CFR 1.63).

Total Attachments: 2
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Attorney Docket No.:

ASSIGNMENT AND DECLARATION FOR PATENT APPLICATION

For good and valuable consideration, the receipt of which is hereby acknowledged, I/we, the undersigned, who have created a certain invention for which an application for United States Letters Patent is entitled:

ETCHING METHOD

as described and claimed in the specification identified by the above Attorney Docket No. do hereby sell, assign and transfer to TOKYO ELECTRON LIMITED, a corporation of Japan, having a place of business at 3-1 Akasaka 5-chome, Minato-ku, Tokyo 107-6325, Japan, its successors, assigns, and legal representatives, the full and exclusive right to said invention and said application and to any and all inventions described in said application for the United States, its territorial possessions and all foreign countries, and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States, its territorial possessions and all foreign countries; and in and to any and all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, and all other applications for Letters Patent relating thereto which have been or shall be filed in the United States, its territorial possessions and/or any foreign countries, and all rights, together with all priority rights, under any of the international conventions, unions, agreements, acts, and treaties, including all future conventions, unions, agreements, acts, and treaties;

Agree that TOKYO ELECTRON LIMITED, hereinafter referred to as Assignee, may apply for and receive Letters Patent for said invention and said inventions, hereinafter referred to as said invention, in its own name, in the United States, its territorial possessions, and all foreign countries; and that, when requested to carry out in good faith the intent and purpose of this assignment, at the expense of said Assignee, its successors, assigns and legal representatives, the undersigned will execute all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, execute all rightful oaths, assignments, powers of attorney and other papers, testify in any legal or quasi legal proceedings; communicate to said Assignee, its successors, assigns or legal representatives all facts known to the undersigned relating to said invention and the history thereof; and generally do everything possible which said Assignee, its successors, assigns, or legal representatives shall consider desirable for aiding in securing, maintaining and enforcing proper patent protection for said invention and for vesting title to said invention and all applications for patents on said invention in said Assignee, its successors, assigns, or legal representatives; and

Covenant with said Assignee, its successors, assigns, or legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

As a below named inventor, I hereby declare that:

> My residence, post office address and citizenship are as stated below, next to my name,
>
> I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:
>
> I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.
>
> This application was made or was authorized to be made by me.

I acknowledge the duty to disclose to the U. S. Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, Section 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code §119(a)-(d) or §365(b) of any foreign application(s) for patent or inventor's certificate or §365(a) of any PCT International application(s) which designated at least one country other than the United States, listed below and have also identified below any foreign application for patent or inventor's certificate, or PCT International application, having a filing date before that of the application on which priority is claimed.

☐ No such Applications have been filed.

☒ Such Applications have been filed as follows:

Prior Foreign Application(s) Application Number	Country	Day/Month/Year Filed	Priority Claimed	
			Yes	No
2017-046473	Japan	10/03/2017	☒	☐
			☐	☐
			☐	☐

I hereby claim the benefit under Title 35, United States Code §119(e) of any United States provisional application(s) listed below.

☒ No such Applications have been filed.

☐ Such Applications have been filed as follows:

Provisional Application(s) Application Number	Priority Claimed Under 35 USC 119(e) Day/Month/Year Filed

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose to the Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, §1.56 which occurred between the filing date of the prior application(s) and the national or PCT international filing date of this application:

☒ No such Applications have been filed.

☐ Such Applications have been filed as follows:

Application Serial No.	Filing Date	Status (Patented, Pending, Abandoned)

I hereby declare that I have reviewed and understand the contents of this Declaration, and that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full Name of Sole/First Inventor: **Kenji OUCHI**	
Inventor's Signature: Kenji Ouchi	Date: Month/Day/Year February 28, 2018
Residence: **Yamanashi, Japan**	
Citizenship: **Japan**	
Post Office Address: **c/o Tokyo Electron Technology Solutions Limited, 650 Mitsuzawa, Hosaka-cho, Nirasaki City, Yamanashi 407-0192 Japan**	